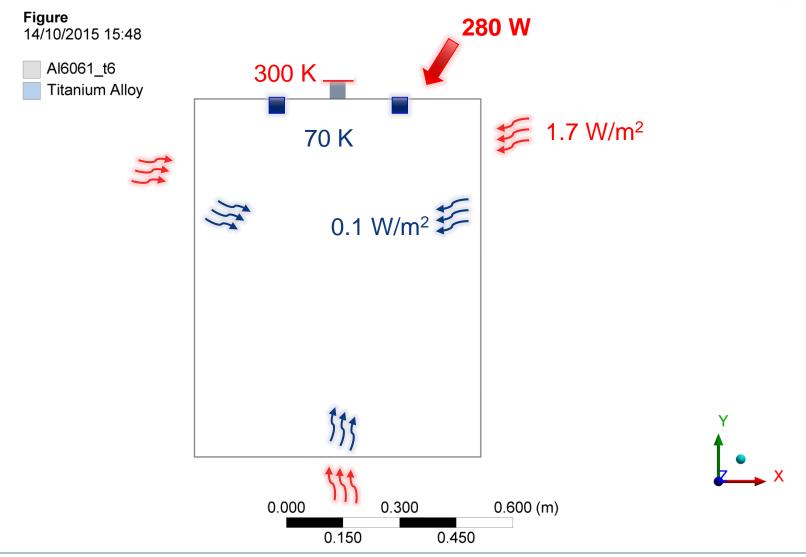
Preliminary 3D calculation of the Thermal Shield

Carlo Zanoni



Loads and Boundary Conditions





Loads and Boundary Conditions

	DQW		RFD		
	2K	80K	2K	80K	
Static					
Radiation	3	35*	3	35*	*see MLI
CWT	0.2	2	0.2	2	
Supports	0.8	30	0.8	30	
FPC	4	100	4	100	
Instrumentation	1	0	1	0	
HOM/Pickup	2.5	10	1.7	10	
Tuner	0.3	10	0.3	10	
Total static	11.8	187	11	187	
Dynamic					
Cavity	6	0	6	0	
FPC	5.6	10	5.6	20	
HOM/Pickup	7.2	120	5.5	80	
Beam	0.5	0	0.5	0	
Total Dynamic	19.3	130	17.6	100	
TOTAL	28.2	282	25.6	252	



Loads and Boundary Conditions

- 300 K external (support edge)
- 77 K at the intercepts locations (real T between 50 and 70 K)
- 280 W to shield from HOM, pickup etc...*
- 0.1 W/m² radiative heat to the tank *
- 1.7 W/m² radiative heat through the MLI (1.5x factor from **)
- 250 W/m²K thermal conductance (i.e. localized thermal resistance at contact location) ***

*from Fede's table G:\Departments\EN\Projects\MME_MechanicalEngineering\Federico.Carra\CrabCavities\ **MLI (also implemented with an Ansys macro as T dependent, but it's a secondary effect): http://arxiv.org/ftp/arxiv/papers/1501/1501.07154.pdf

***not implemented for now

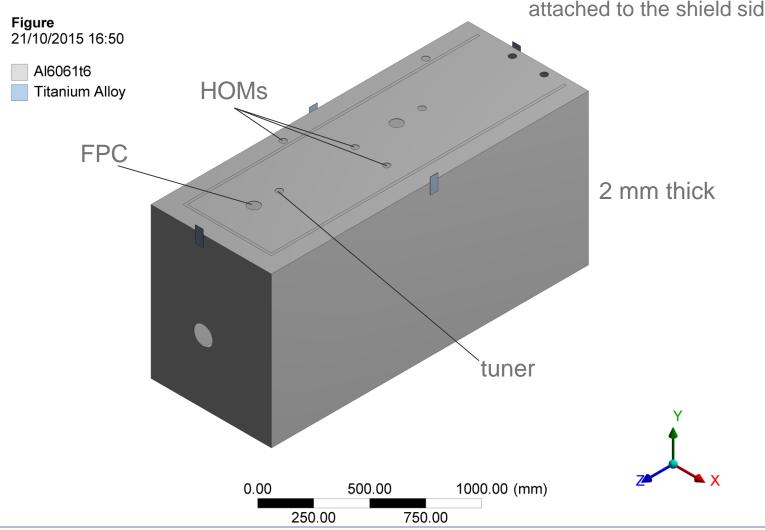


Simple U pipe – Al 6061



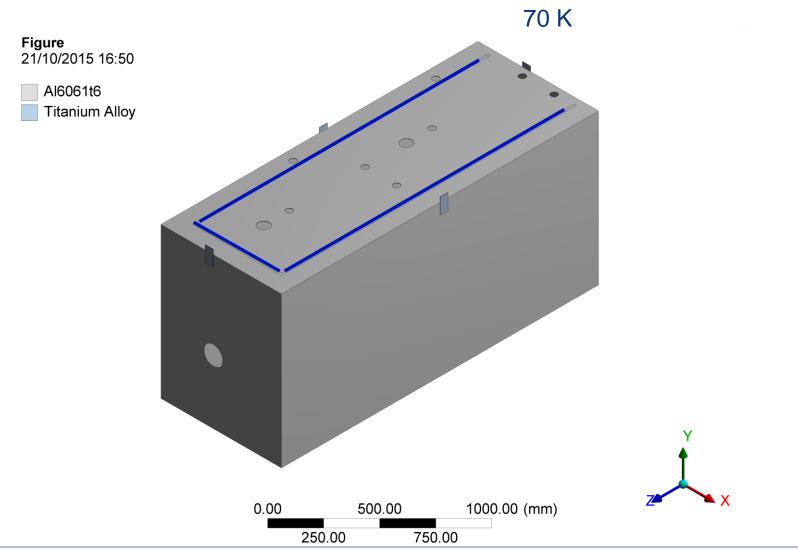
Geometry

The support is made through 100mm long Ti blades, attached to the shield sides



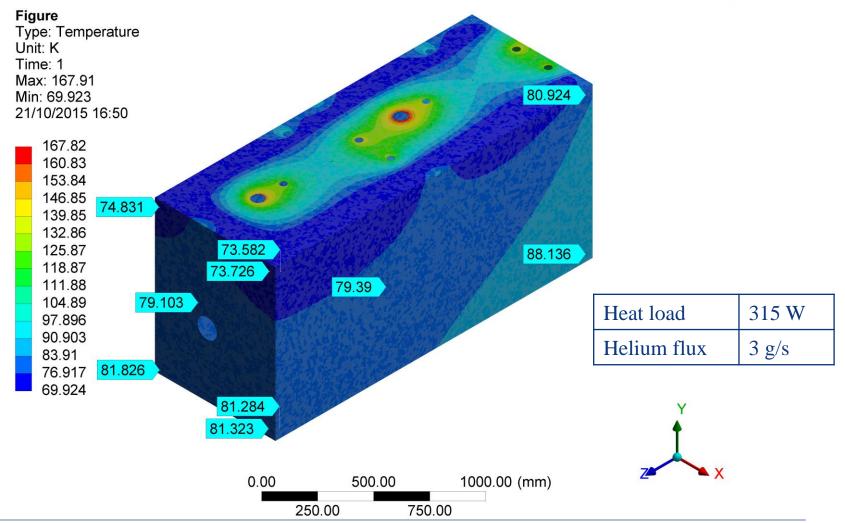


Geometry



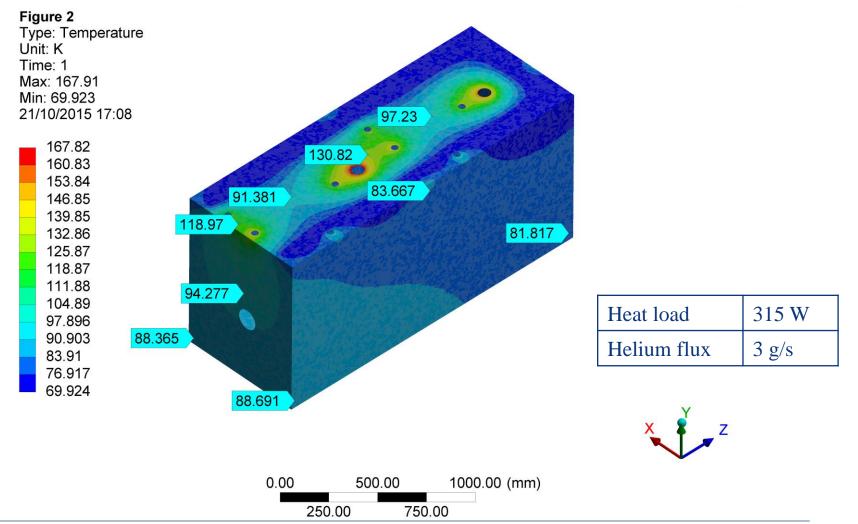


Temperature Distribution



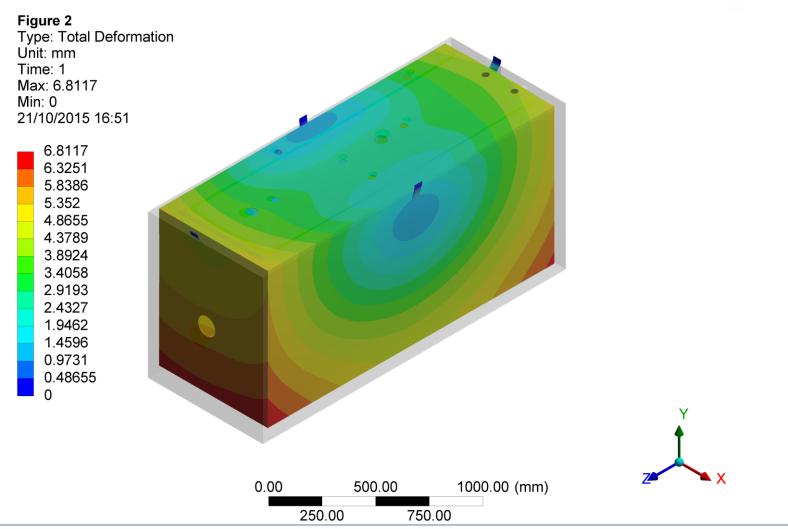


Temperature Distribution



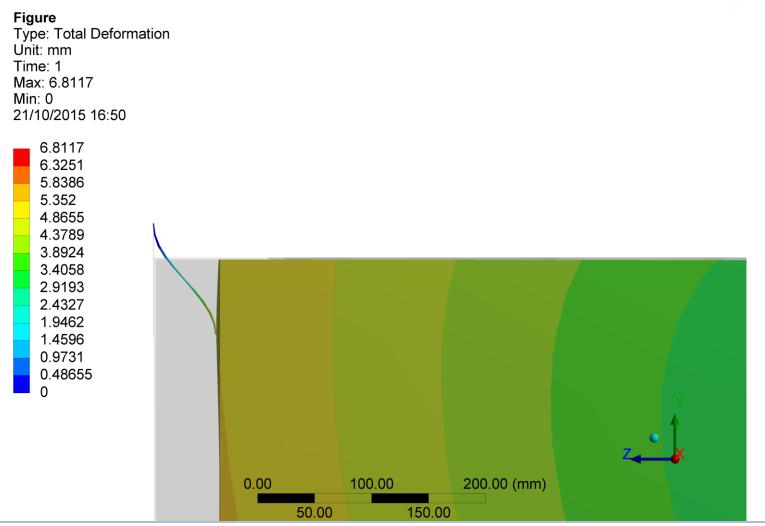


Deformation



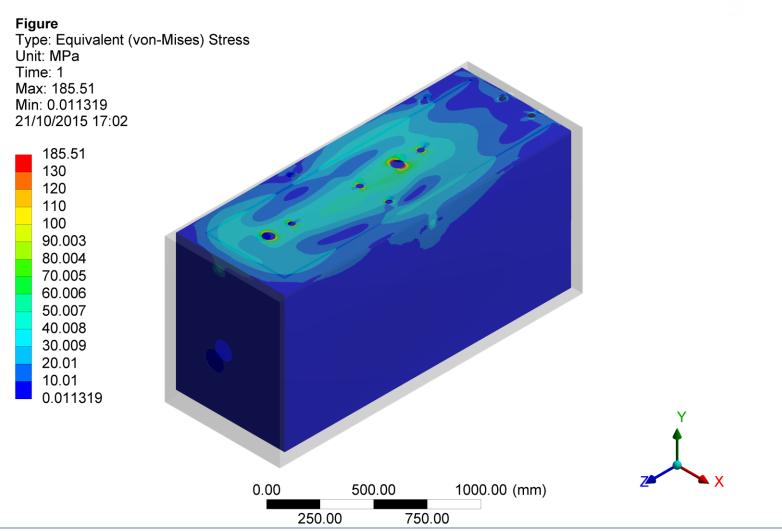


Deformation





Stress

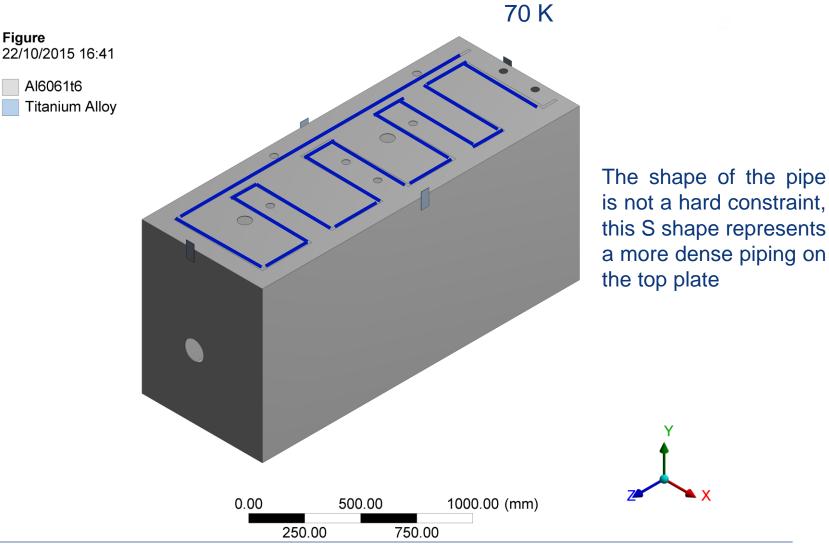




S pipe – Al 6061

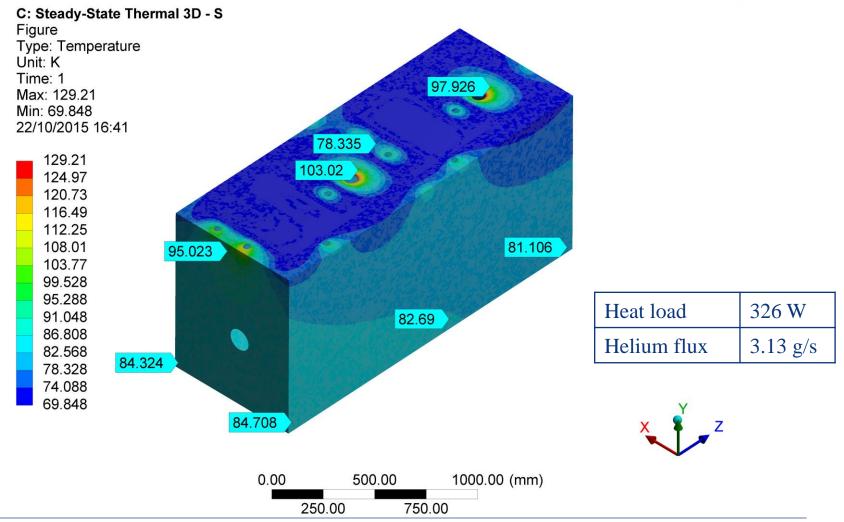


Geometry



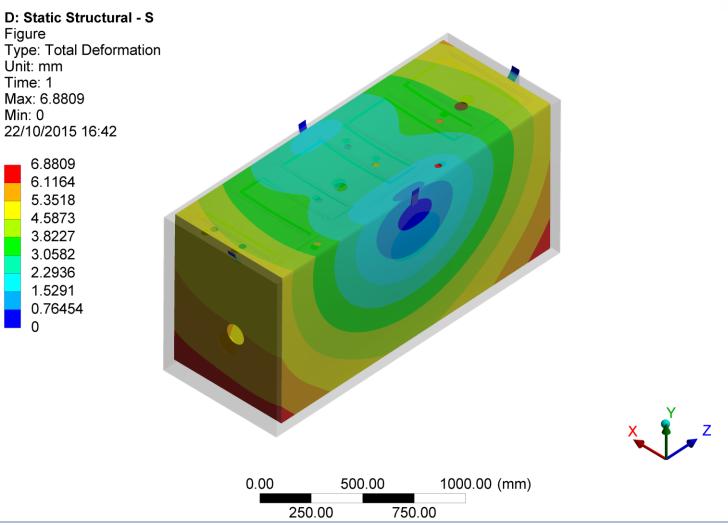


Temperature Distribution



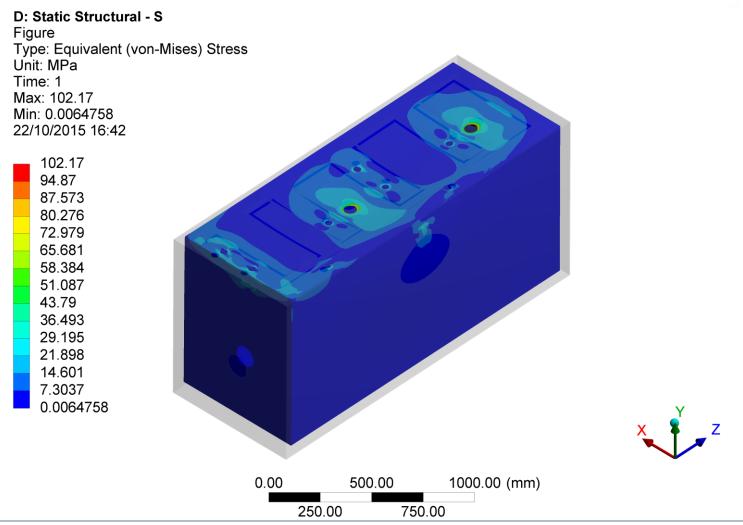


Deformation





Stress

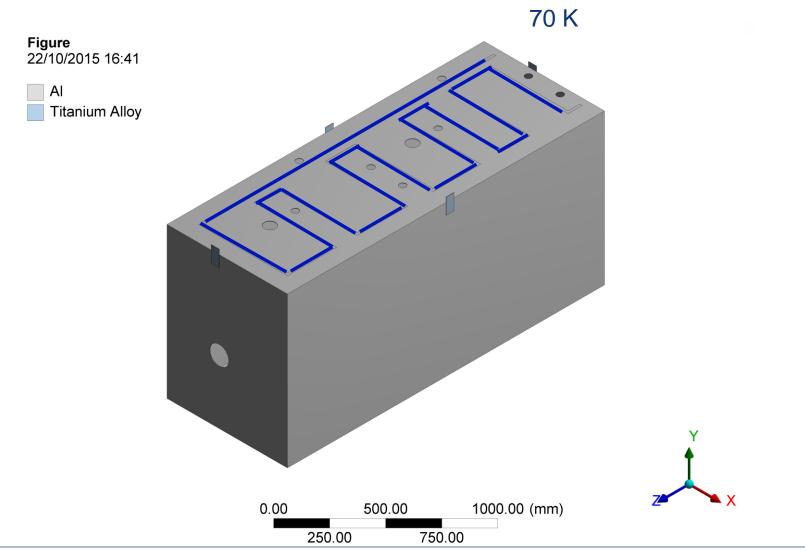




S pipe – Al 1060

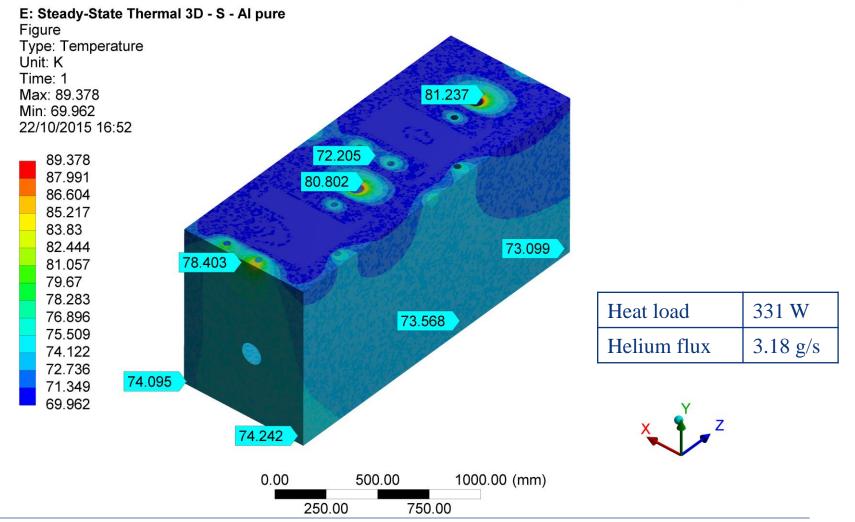


Geometry



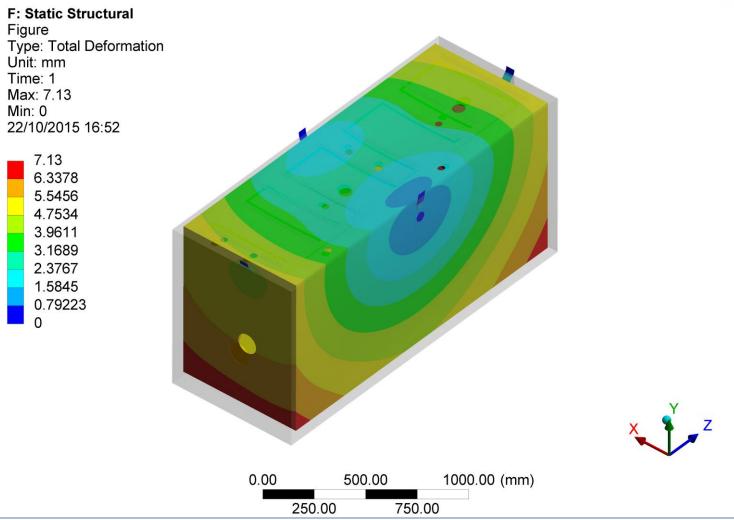


Temperature Distribution



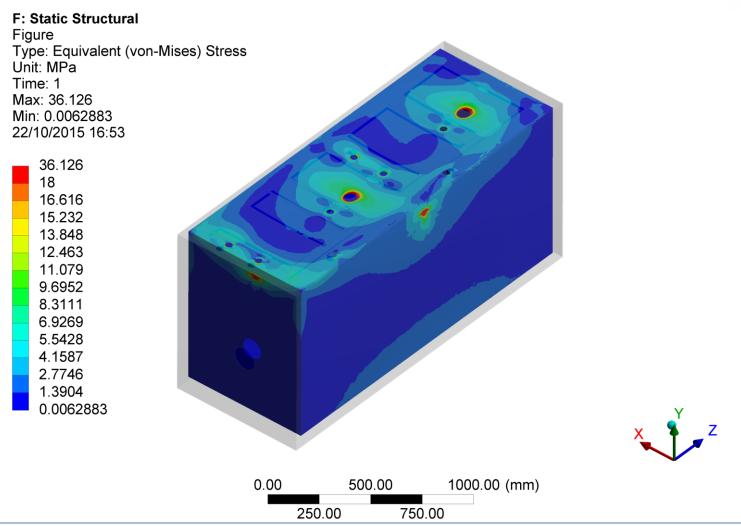


Deformation





Stress

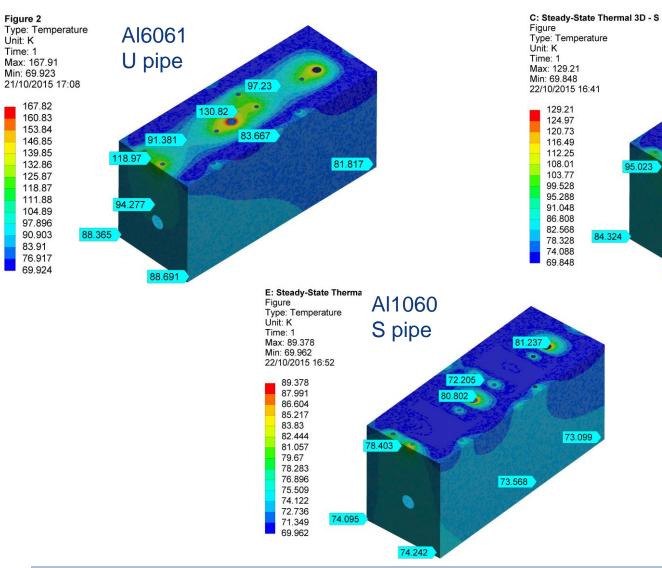




Comparison



Temperature



AI6061

S pipe

84.708

78.335

103.02

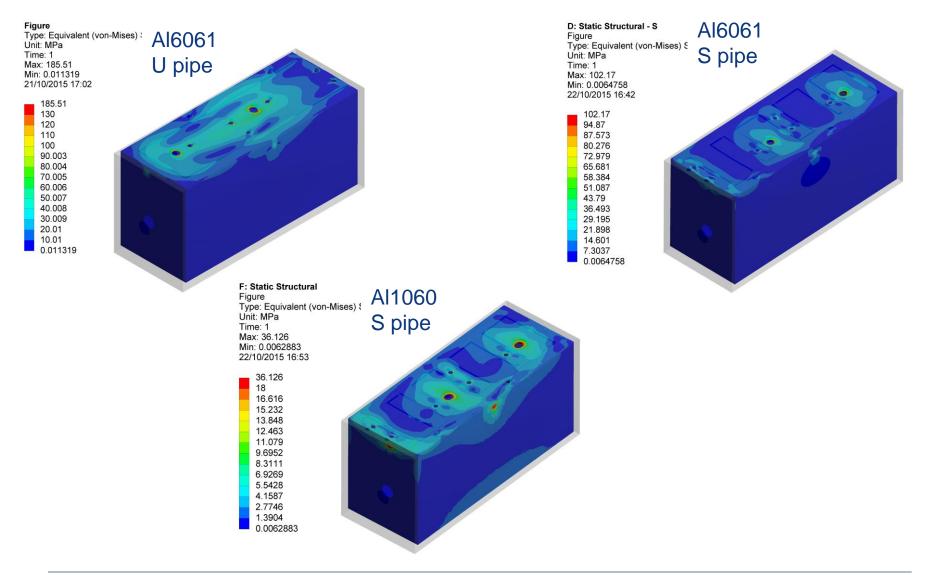
97.926

82.69

81.106



Stress





Comments

- The use of a more complex pipe greatly enhances the performance (i.e. smaller T gradient and lower stress)
- Pure AI (1060) has 5x* conductivity of 6061. The result is a further improvement of T and stress
- Al 1060 has low yield and all my researches point towards thermal shields in Al 6061. The Al series 6 is easily weldable.
- Best choice?